503680856 02/04/2016

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUTAKA OKAZAKI	01/26/2016

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15011833

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070

Email: APSI@fr.com

Correspondent Name: JOHN F. HAYDEN

Address Line 1: FISH & RICHARDSON P.C.

Address Line 2: P.O.BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER:	12732-1639001
NAME OF SUBMITTER:	JANELLE A. JACKSON
SIGNATURE:	/Janelle A. Jackson/
DATE SIGNED:	02/04/2016

Total Attachments: 1

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PATENT 503680856 REEL: 037668 FRAME: 0692

ASSIGNMENT

For valuable consideration, I, <u>Yutaka OKAZAKI of Isehara, Kanagawa, Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and
interest throughout the world in the inventions and improvements which are subject of an application for
United States Patent signed by me this day, entitled SEMICONDUCTOR DEVICE AND METHOD FOR
MANUFACTURING THE SAME, filed February 1, 2016, and assigned U.S. Serial
Number 15/011,833, and I authorize and request the Assignee or the attorneys appointed in
said application to hereafter complete this assignment by inserting above the filing date and serial number of
said application when known; this assignment including said application, any and all United States and
foreign patents, utility models, and design registrations granted for any of said inventions or improvements,
and the right to claim priority based on the filing date of said application under the International Convention
for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and
all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its
own name for patents, utility models, design registrations and like rights of exclusion and for inventors'
certificates for said inventions and improvements; and I agree for myself and my respective heirs, legal
representatives and assigns, without further compensation to perform such lawful acts and to sign such
further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may
reasonably request to effectuate fully this assignment.

Signature	Yutaka Okazaki
Name:	Yutaka OKAZAKI
Date:	01/26/2016

RECORDED: 02/04/2016

PATENT REEL: 037668 FRAME: 0693